

Date Created : 2009/07/14
 Date Issued On : 2009/08/17
 PCN# : Q3092902

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:
 Name: Chun, SeungJoo
 E-mail: tmdwn1@fairchildsemi.co.kr
 Phone:

PCN Originator:
 Name: Park, ByoungYong
 E-mail: ByoungYong.Park@fairchildsemi.com
 Phone:

Implementation of change:
 Expected 1st Device Shipment Date: 2009/10/23

Earliest Year/Work Week of Changed Product: 943

Change Type Description: Wafer Diameter

Description of Change (From): 4inch diameter, Bucheon, Korea 82-3, Dodang Dong, Wonmi Ku, Kyeonggy Do, Korea

Description of Change (To): 5inch diameter, Bucheon, Korea 82-3, Dodang Dong, Wonmi Ku, Kyeonggy Do, Korea

Reason for Change : wafer diameter change

Qual/REL Plan Numbers : Q20090182

Qualification :

There is no difference between 4inch and 5inch.

Results/Discussion for Qual Plan Number Q20090182

Test: (High Temperature Reverse Bias) Conditions: 125C, 1200V Standard: JESD22-A108					
Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20090182AAHTRB	FFPF14X150STU	0/77			
			0/77		
				0/77	
Q20090182ABHTRB		0/77			
			0/77		
				0/77	
Q20090182ACHTRB		0/77			
			0/77		

			0/77	
--	--	--	------	--

Product Id Description : 1600V Rated FRD(Fast Recovery Diode) for wafer business

Affected FSIDs :

PCR10160W	PCR30160W	
-----------	-----------	--